

**SUBSTITUTE SPECIFICATION
(CLEAN VERSION)**

Abstract

**METHOD FOR PRODUCING AN INTEGRATED CIRCUIT WITH A
REWIRING DEVICE AND CORRESPONDING INTEGRATED CIRCUIT**

The present invention provides a method for producing an integrated circuit with a rewiring device. In the method, there is provision of a carrier device with defined cutouts, application of at least one integrated circuit upside down to the carrier device such that the defined cutouts of the carrier device are located above at least one connection device of the integrated circuit application of an insulation device to that side of the carrier device which is not covered by the integrated circuit, omitting the at least one connection device in the cutout); application of the patterned rewiring device to the insulation device; application of a patterned solder resist device to the patterned rewiring device; and patterned application of solder balls on sections of the rewiring device which are not covered by the patterned solder resist device. The present invention likewise provides such an apparatus.